

MOTOROLA SEMICONDUCTOR TECHNICAL DATA

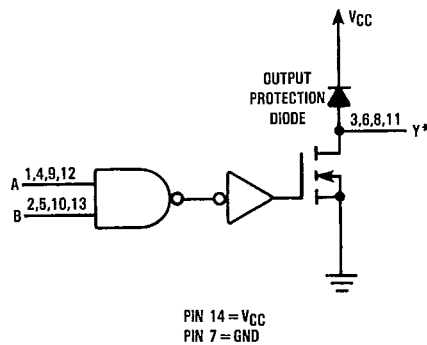
Quad 2-Input NAND Gate with Open-Drain Outputs
High-Performance Silicon-Gate CMOS

The MC54/74HC03 is identical in pinout to the LS03. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC03 NAND gate has, as its output, a high-performance MOS N-Channel transistor. This NAND gate can, therefore, with a suitable pullup resistor, be used in wired-AND applications. Having the output characteristic curves given in this data sheet, this device can be used as an LED driver or in any other application that only requires a sinking current.

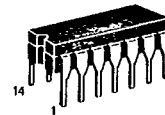
- Output Drive Capability: 10 LSTTL Loads with Suitable Pullup Resistor
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 28 FETs or 7 Equivalent Gates

LOGIC DIAGRAM

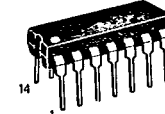


*Denotes open-drain outputs.

MC54/74HC03



J SUFFIX CERAMIC CASE 632-08



N SUFFIX PLASTIC CASE 646-06



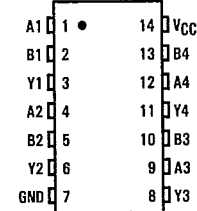
D SUFFIX SOIC CASE 751A-01

ORDERING INFORMATION

MC74HCXXN Plastic
 MC54HCXXJ Ceramic
 MC74HCXXD SOIC

T_A = -65° to 125°C for all packages.
 Dimensions in Chapter 7.

PIN ASSIGNMENT



FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	Z
L	H	Z
H	L	Z
H	H	L

Z = High Impedance

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MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{in}	DC Input Voltage (Referenced to GND)	-1.5 to V _{CC} +1.5	V
V _{out}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
I _{in}	DC Input Current, per Pin	±20	mA
I _{out}	DC Output Current, per Pin	±25	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±50	mA
P _D	Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package†	750 500	mW
T _{stg}	Storage Temperature	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package) (Ceramic DIP)	260 300	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

†Derating — Plastic DIP: -10 mW/°C from 65° to 125°C
Ceramic DIP: -10 mW/°C from 100° to 125°C
SOIC Package: -7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 4.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V _{CC}	V
T _A	Operating Temperature, All Package Types	-55	+125	°C
t _r , t _f	Input Rise and Fall Time (Figure 1)	V _{CC} =2.0 V V _{CC} =4.5 V V _{CC} =6.0 V	0 1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				25°C to -55°C	≤85°C	≤125°C	
V _{IH}	Minimum High-Level Input Voltage	V _{out} =0.1 V, I _{out} =0 μA or V _{out} =V _{CC} -0.1 V, R _{pu} per Figure 2	2.0	1.5	1.5	1.5	V
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
V _{IL}	Maximum Low-Level Input Voltage	V _{out} =0.1 V, I _{out} =0 μA or V _{out} =V _{CC} -0.1 V, R _{pu} per Figure 2	2.0	0.3	0.3	0.3	V
			4.5	0.9	0.9	0.9	
			6.0	1.2	1.2	1.2	
V _{OL}	Maximum Low-Level Output Voltage	V _{in} =V _{IH} or V _{IL} I _{out} ≤ 20 μA	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
		6.0	0.1	0.1	0.1		
		V _{in} =V _{IH} or V _{IL} I _{out} ≤ 4.0 mA I _{out} ≤ 5.2 mA	4.5	0.26	0.33	0.40	
6.0	0.26		0.33	0.40			
I _{in}	Maximum Input Leakage Current	V _{in} =V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} =V _{CC} or GND I _{out} =0 μA	6.0	2	20	40	μA
I _{OZ}	Maximum Three-State Leakage Current	Output in High-Impedance State V _{in} =V _{IL} or V _{IH} V _{out} =V _{CC} or GND	6.0	±0.5	±5.0	±10.0	μA

NOTE: Information on typical parametric values can be found in Chapter 4.

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AC ELECTRICAL CHARACTERISTICS ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Symbol	Parameter	VCC V	Guaranteed Limit			Unit
			25°C to -55°C	≤ 85°C	≤ 125°C	
t _{PLZ} , t _{PZL}	Maximum Propagation Delay, Input A or B to Output Y (Figures 1 and 2)	2.0	125	155	190	ns
		4.5	25	31	38	
		6.0	21	26	32	
t _{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 2)	2.0	75	95	110	ns
		4.5	15	19	22	
		6.0	13	16	19	
C _{in}	Maximum Input Capacitance	—	10	10	10	pF
C _{out}	Maximum Three-State Output Capacitance (Output in High-Impedance State)	—	10	10	10	pF

NOTES:

1. For propagation delays with loads other than 50 pF, see Chapter 4.
2. Information on typical parametric values can be found in Chapter 4.

C _{PD}	Power Dissipation Capacitance (Per Gate) Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ For load considerations, see Chapter 4.	Typical @ 25°C, V _{CC} = 5.0 V	pF
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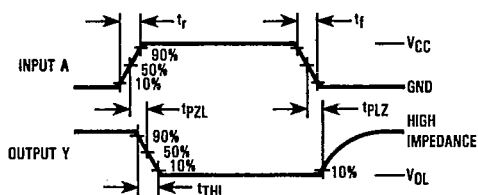
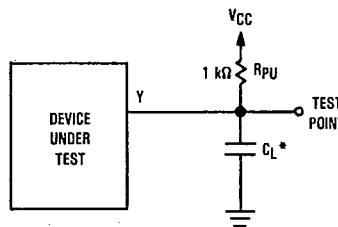
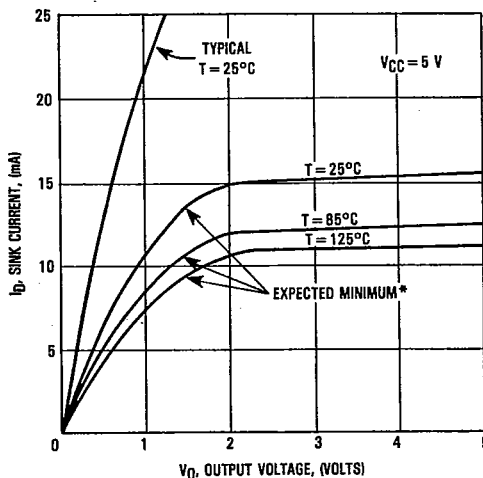


Figure 1. Switching Waveforms



*Includes all probe and jig capacitance.

Figure 2. Test Circuit



*The expected minimum curves are not guarantees, but are design aids.

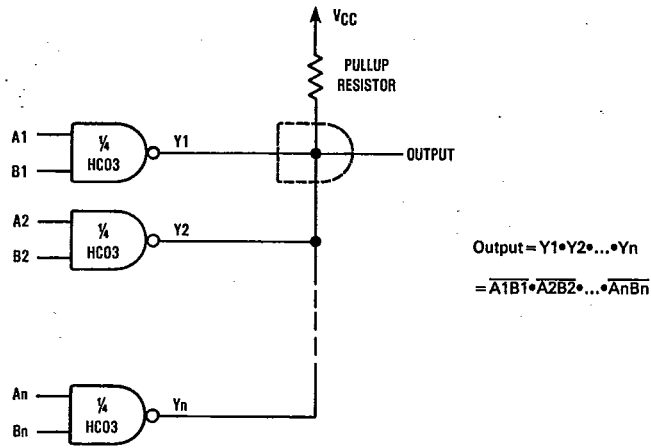
Figure 3. Open-Drain Output Characteristics

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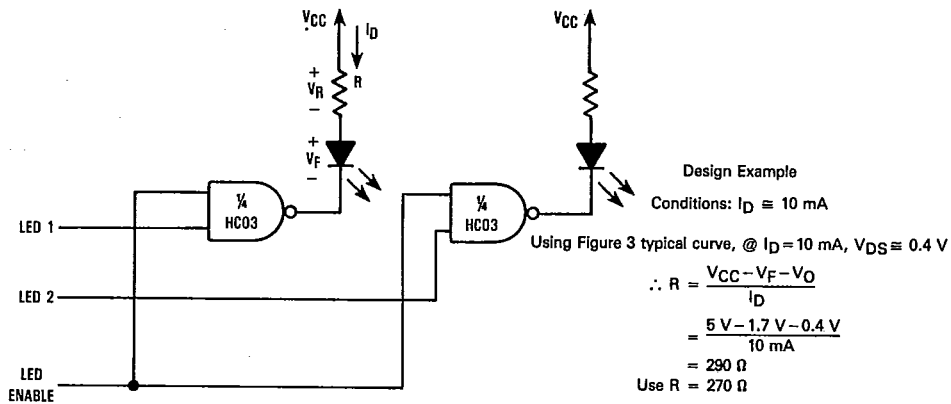
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TYPICAL APPLICATIONS

Wired AND



LED Driver with Blanking



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